

said board, an entire surface of said ground part being
covered with a magnetic thin film; and
magnetic thin films deployed at least on part of said board or said
conductor part.

Cancel claims 20-21.

REMARKS

Entry of the foregoing amendments, and reexamination and reconsideration of the subject application, pursuant to and consistent with 37 C.F.R. § 1.104 and § 1.112, and in light of the following remarks, are respectfully requested.

This application is a divisional application, as noted above, and is directed to claim 20 in the parent application. Accordingly, independent claim 19 has been amended to incorporate the limitations of claim 20, respectively, and the dependent claims have been deleted or amended accordingly.

An early action on the merits is respectfully requested.

Respectfully submitted,



Bradley N. Ruben, Reg. No. 32,058
Bradley N. Ruben, PC
463 First St., Suite 5A
Hoboken, NJ 07030-1859
201-239-0707 (fax -0734)
mail@rubenpatent.com
8 August 2003

APPENDIX SHOWING MARKUPS OF AMENDMENTS

IN THE SPECIFICATION:

Page 1, after the title and prior to the background section, add the paragraph:

This application is a divisional of application 09/825,418, filed 3 April 2001, a Convention application based on Japanese applications 101756 and 101765, both filed 4 April 2000.

IN THE CLAIMS:

Cancel claims 1-18.

19. (Amended.) A wiring board, comprising:

a board of at least one layer comprising a conductor part, said conductor part having a ground part that is either a ground surface or has ground patterns deployed on one surface of said board, an entire surface of said ground part being covered with a magnetic thin film; and
magnetic thin films deployed at least on part of said board or said conductor part.

Cancel claims 20-21.